## **ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

#### Electronic Version v18

Stylesheet Version v18.0

Title of Invention

SEMICONDUCTOR PACKAGE, METHOD OF MANUFACTURING THE SAME, AND SEMICONDUCTOR DEVICE

Application Number:

Confirmation Number:

First Named Applicant:

Takahiro IIJIMA

Attorney Docket Number:

021083a

Art Unit:

Examiner:

Search string:

(5796587).pn

#### **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
A2	1	5796587	1998-08-18	Lauffer et al.		361	763

# **Signature**

Examiner Name	Date		
MA	12/08/04		

INFORMATION Atty. Docket No. 021083A Serial No. 10/709,912

DISCLOSURE
CITATION
PTO-1449 Filing Date: June 4, 2004 Group Art Unit: 2829

## **U.S. PATENT DOCUMENTS**

Examiner Initial		Document No.	Name	Date	Class	Subclass	Filing Date (If appropriate)
	AA						
	AB						
	AC						
	AD						19
	AE					· · · · · · · · · · · · · · · · · · ·	

## FOREIGN PATENT DOCUMENTS

	Document No.			Country	Translation (Yes or No)
	AF				
<del></del>	AG				
	AH				
	AI				
	AJ				

## OTHER DOCUMENTS

<u> </u>	AK AL	Nakamura et al.; "POLYIMIDE FILMS PREPARED BY ELECTROPHORETIC DEPOSITION AND THEIR DIELECTRIC BREAKDOWN", SPIE, Volume 2780, pages 71-75, September 11-14, 1995.
Examiner	1	Date Considered 12/08/04